Amendment under 37 C.F.R. §1.111

Application No.: 10/823,729

Art Unit: 2818

Attorney Docket No.: 042341

REMARKS

Claims 1-4, 12, 13, 28, 29 and 34 are pending in the present application and are rejected.

Claims 1-4 are herein amended. No new matter has been added

Amendments

Applicants herein revise claims 1 and 2 in order to improve their clarity and form.

Applicants herein amend claims 3 and 4 in order to rewrite these claims in independent form

including all of the limitations of the base claim. Applicants submit that this amendment does

not raise new issues requiring further search or consideration. No new matter has been added.

Applicants' Response to Claim Rejections under 35 U.S.C. §102

Claims 1-4, 12, 13, 28 and 29 were rejected under 35 U.S.C. 102(e) as being

anticipated by Miyashita et al. (U.S. Patent No. 5,861,054).

It is the position of the Office Action that Miyashita discloses the embodiments as

claimed. Miyashita discloses a semiconductor device fabrication method comprising: the step of

polishing a surface of a polishing film 12 by using a CVD-oxide film 3 as a stopper film (first

CMP step) (column 8, lines 10-19 and FIGs. 5G-5H); the step of etching the CVD-oxide film 3

(column 8, lines 20-24 and FIG. 5I); the step of polishing an upper part of the polishing film 12

by using a nitride film 2 as a stopper film (second CMP step) (column 8, lines 25-33 and FIG.

5J). In Miyashita, a polishing slurry used in the first CMP step and a polishing slurry used in the

second CMP step are the same kind of polishing slurry (column 8, lines 29-33).

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In response, Applicants respectfully submit that Miyashita does not disclose or suggest

further polishing the surface of the film-to-be-polished with the polishing pad while a second

polishing material comprising the polishing slurry and water is being supplied onto the polishing

pad as required by claim 1.

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In the claimed embodiments, the polishing materials used in the first and second

polishing steps are different. In the first polishing step, a polishing material comprising polishing

slurry (which comprises abrasive grains and a surfactant) is used. In the second polishing step, a

polishing material comprising the same polishing slurry and water is used. Thus, the first and

second polishing materials are different, even though the same polishing slurry is used in the first

and second polishing materials. Rather, in Miyashita, only polishing slurry is used in the second

CMP step. In Miyashita, water is not supplied onto a polishing pad in the second CMP step (see

column 8, lines 25-33). In other words, in Miyashita, the first and second polishing steps use the

same polishing material. Thus, Miyashita does not disclose or suggest the "further polishing"

step of claim 1. Accordingly, Applicants respectfully submit that claim 1 is not anticipated by

Miyashita, since the reference does not teach each and every limitation of claim 1. Favorable

reconsideration is respectfully requested.

Similarly, Applicants respectfully submit that Miyashita does not teach or suggest further

polishing the surface of the film-to-be-polished with the polishing pad while a second polishing

material comprising a mixture of the polishing slurry and water is supplied onto the polishing

pad as required by claim 2.

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In Miyashita, only polishing slurry is used in the second CMP step. In Miyashita, a

mixture of polishing slurry and water is not supplied onto the polishing pad in the second CMP

step (see column 8, lines 25-33). The same polishing material is used in the first and second

polishing steps of Miyashita. Accordingly, Applicants respectfully submit that claim 2 is not

anticipated by Miyashita, since the reference does not teach each and every limitation of claim 2.

Favorable reconsideration is respectfully requested.

Furthermore, in addition to the above comments regarding polishing slurry and water,

Applicants respectfully submit that Miyashita does not disclose or suggest that "the water is

supplied to a position outer of a position for the polishing slurry to be supplied to" as recited in

claim 3. Accordingly, Applicants respectfully submit that claim 3 is not anticipated by

Miyashita, since the reference does not teach each and every limitation of claim 3. Favorable

reconsideration is respectfully requested.

Finally, in addition to the above comments regarding a mixture of polishing slurry and

water, Applicants respectfully submit that Miyashita does not disclose or suggest "a supply

amount of the water is 2 or more times as much as a supply amount of the polishing slurry" as

recited in claim 4. Accordingly, Applicants respectfully submit that claim 4 is not anticipated by

Miyashita, since the reference does not teach each and every limitation of claim 4. Favorable

reconsideration is respectfully requested.

Next, Applicants discuss the dependent claims. Claims 12 and 28 depend on claim 1,

while claims 13 and 29 depend on claim 2. As discussed above, Miyashita does not disclose the

features recited in claims 1 and 2. Accordingly, Applicants respectfully submit that claims 12,

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13, 28 and 29 are patentable at least due to their dependency on claims 1 and 2, which Applicants

submit are patentable for at least the above reasons. Accordingly, withdrawal of the rejection of

claims 12, 13, 28 and 29 is hereby solicited. Favorable reconsideration is respectfully requested.

Applicants' Response to the Claim Rejection under 35 U.S.C. 103

Claim 34 was rejected under 35 U.S.C. 103(a) as being unpatentable over Miyashita

et al (U.S. Patent No. 5,861,054).

It is the position of the Office Action that Miyashita discloses the invention as claimed,

with the exception of disclosing the ratio of polishing slurry to water. The Office Action argues

that this would have been obvious.

In response, Applicants respectfully submit that claim 34 is patentable at least due to its

dependency on claim 1, which Applicants submit is patentable for at least the reasons discussed

above. Favorable reconsideration is respectfully requested.

CONCLUSION

In view of the aforementioned amendments and accompanying remarks, Applicants

respectfully submit that the claims, as herein amended, are in condition for allowance.

Applicants request such action at an early date.

For at least the foregoing reasons, the claimed invention distinguishes over the cited art

and defines patentable subject matter. Favorable reconsideration is earnestly solicited.

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Should the Examiner deem that any further action by applicants would be desirable to place the application in condition for allowance, the Examiner is encouraged to telephone applicants' undersigned attorney.

If this paper is not timely filed, Applicants respectfully petition for an appropriate extension of time. The fees for such an extension or any other fees that may be due with respect to this paper may be charged to Deposit Account No. 50-2866.

Respectfully submitted,

WESTERMAN, HATTORI, DANIELS & ADRIAN, LLP

Ryan B. Chirnomas
Attorney for Applicants

Registration No. 56,527 Telephone: (202) 822-1100

Facsimile: (202) 822-1111

RBC/ttw